

GTRB266702FCV1A

Rev. V1

Features

- GaN on SiC HEMT Technology
- Pulsed CW Performance: 2690 MHz, 48 V, 10 μs Pulse Width, 10% Duty Cycle, Combined Outputs
- Output Power @ P4dB = 610 W
- Efficiency @ P4dB = 65.8%
- · Thermally Enhanced Package
- Pb-free and RoHS* Compliant

Applications

· Cellular, 5G Infrastructure

Description

The GTRB266702FCV1A is a GaN on SiC HEMT amplifier for use in multi-standard cellular power amplifier applications. It features input and output matching, high efficiency, and a thermally-enhanced package with earless flange.

Typical RF Performance¹ Single-carrier WCDMA Specifications

 V_{DD} = 48 V, I_{DQ} = 360 mA, $V_{GS(PEAK)}$ = -5.1 V, P_{OUT} = 48.5 dBm avg, T_{C} = 25°C, Channel Bandwidth = 3.84 MHz, Peak/Average = 10 dB @ 0.01% CCDF

Frequency (MHz)	Gain (dB)	Efficiency (%)	OPAR (dB)	ACPR (dBc)
2620	15.4	52.2	9.0	-29.6
2655	15.5	51.8	9.0	-29.9
2690	15.7	53.3	9.1	-29.5

Measurements taken with device soldered in Doherty evaluation board for 2620 - 2690 MHz.

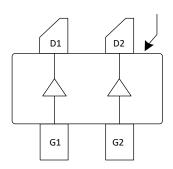
Ordering Information

Part Number	Package
GTRB266702FCV1A-R0	50 piece reel
GTRB266702FCV1A-R2	250 piece reel



Package Type: H-37248C-4

Functional Schematic



Pin Configuration

Pin #	Function
G1	Gate Device 1 (main)
G2	Gate Device 2 (peak)
D1	Drain Device 1 (main)
D2	Drain Device 2 (peak
S	Source (flange)

^{*} Restrictions on Hazardous Substances, compliant to current RoHS EU directive.



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RF Electrical Specifications²:

Freq. = 2690 MHz, V_{DD} = 48 V, I_{DQ} = 360 mA, $V_{GS(PEAK)}$ = -5 V, P_{OUT} = 48.5 dBm (70.8 W), T_C = 25°C, Channel Bandwidth = 3.84 MHz, Peak/Average = 10 dB @ 0.01% CCDF

Parameter	Units	Min.	Тур.	Max.
Gain	dB	13.0	14.2	_
Drain Efficiency	%	45.0	49.8	_
Adjacent Channel Power Ratio	dBc	_	-27	-22
Output PAR @ 0.01% CCDF	dB	6.9	7.5	_

^{2.} Performance in MACOM Doherty Production Test Fixture

DC Electrical Characteristics: T_A = 25°C

Parameter	Test Conditions	Units	Min.	Тур.	Max.
Drain-Source Breakdown Voltage	V_{GS} = -8 V, I_D = 10 mA main, peak	V	150	_	_
Drain-Source Leakage Current	V _{GS} = -8 V, V _{DS} = 10 V main peak	mA	_	_	5.7 8.0
Gate Threshold Voltage	V_{DS} = 10 V main, I_D = 36 mA peak, I_D = 50 mA	V	-3.8	-2.5 -2.7	-2.1

Recommended Operating Voltages

Parameter	Test Conditions	Units	Min.	Тур.	Max.
Drain Operating Voltage	_	V	0	_	50
Gate Quiescent Voltage	V _{DS} = 48 V, I _D = 360 mA	V	-3.8	-2.9	-2.2



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Absolute Maximum Ratings^{3,4,5}

Parameter	Absolute Maximum
Drain-Source Voltage	125 V
Gate-Source Voltage	-10 V to +2 V
Operating Voltage	55 V
Gate Current (main)	36 mA
Gate Current (peak)	50.4 mA
Drain Current (main)	13.5 A
Drain Current (peak)	18.9 A
Junction Temperature	+275°C
Storage Temperature	-65°C to +150°C

^{3.} Exceeding any one or combination of these limits may cause permanent damage to this device.

Thermal Characteristics

Parameter	Test Conditions	Units	Min.	Тур.	Max.
Thermal Resistance (R _{eJC}) main peak	T _C = +85°C, 48 V, 134 W DC 140 W DC	°C/W	_	1.05 1.00	

Bias Sequencing

Bias ON

- 1. Ensure RF is turned off
- 2. Apply pinch-off voltage of -5 V to the gate
- 3. Apply nominal drain voltage
- 4. Bias gate to desired quiescent drain current
- 5. Apply RF

Bias OFF

- 1. Turn RF off
- 2. Apply pinch-off voltage to the gate
- 3. Turn-off drain voltage
- 4. Turn-off gate voltage

Handling Procedures

Please observe the following precautions to avoid damage:

Static Sensitivity

These electronic devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.

^{4.} MACOM does not recommend sustained operation near these survivability limits.

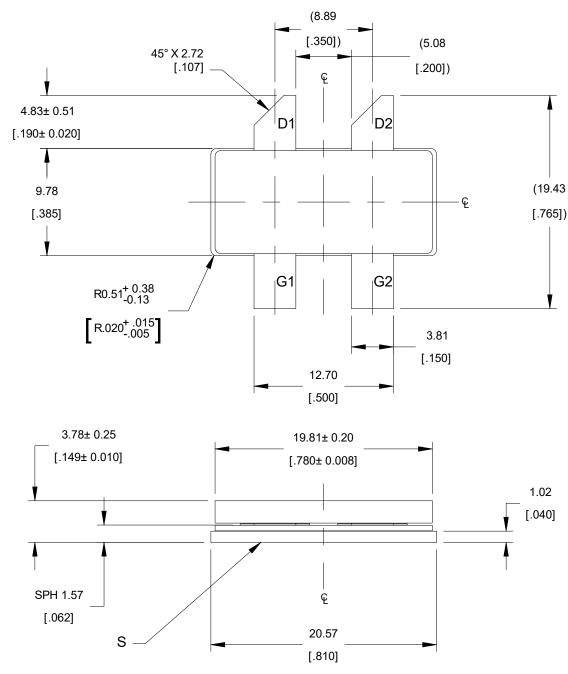
^{5.} Product's qualification were performed @ +225°C. Operation @ T_J (+275°C) reduces median time to failure.



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Lead-Free Outline Drawing H-37248C-4



Interpret dimensions and tolerances per ASME Y14.5M-1994 Primary dimensions are mm; alternate dimensions are inches All tolerances ± 0.127 [0.005]

Lead thickness: 0.13 ± 0.05 mm [0.005 ± 0.002 inch] Gold plating thickness: 1.14 ± 0.38 micron [45 ± 15 microinch]



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